Standard Process for Plastic Encapsulated MMICs
DFN, MSOP, QFN, QSOP, SOIC, SOT Packages

1. Wafers Qualified per “Standard Process for Commercial Die”
   * Record Wafer Lot Numbers

2. Per Product List of Materials

3. Per P15N04, Handling, Storage, Packaging, Preservation & Delivery

4. Per IC Sub-Contractor’s Standard Process

5. Per IC Sub-Contractor’s Commercial GaAs Visual Inspection

6. Die Attach and Wire Bond Per IC Sub-Contractor’s Standard Process
   * Reference HMC Assembly Drawing

7. Per IC Sub-Contractor’s Commercial GaAs Visual Inspection
   * Reference HMC Assembly Drawing

8. Per IC Sub-Contractor’s Standard Process

9. Per IC Sub-Contractor’s Standard Process
   * Reference HMC PO and Outline / Marking Drawing

10. Per IC Sub-Contractor’s Standard Process
    * Reference HMC PO and Outline / Marking Drawing

11. Per IC Sub-Contractor’s Standard Process
    * Reference HMC PO and Outline / Marking Drawing

12. Per IC Sun-Contractor’s Standard Process
    * Reference HMC PO and Outline / Marking Drawing

13. Per IC Sub-Contractor’s Standard Process
    * Reference HMC PO

14. Per Product Test Procedure
    * HMC Data Sheet Limits
    * Room Temperature

15. Per Hittite Catalog Specification, Section 10
    * When Applicable

16. Per P15N04, Handling, Storage, Packaging, preservation & Delivery

17. Per P03N01, Quotation, Order Entry and Contract Review
    * Customer PO

18. Per P09N02, Filling a Work Authorization
    * Customer PO

19. Per P15N04, Handling, Storage, Packaging, Preservation & Delivery
    * Customer PO

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
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